

	L #	Hits	Search Text	DBs
1	L1	168531	"438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
2	L2	82686	1 and (contact or interconnect\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
3	L3	4655	2 and contact near opening	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
4	L4	744	3 and isolation near trench\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
5	L5	1	4 and (excess near (isolat\$3 or insulat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
6	L6	493	4 and (CMP or polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
7	L7	36	6 and (part\$3 near remov\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
8	L8	3	7 and (dish\$3 or dish-shaped or recess or concave) near surface\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
9	L9	281	(hou-chuan-ping or jang-syun-ming or chen-ying-ho or tseng-tung-ching).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
10	L1 1	176	9 and (contact or (contact near opening))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
11	L1 2	34	11 and isolation near trench\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
12	L1 3	0	12 and (excess near (isolat\$3 or insulat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
13	L1 5	33	12 and (CMP or polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
14	L1 6	1	15 and (dish\$3 or dish-shaped or recess or concave) near surface\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
15	L1 7	345939	(contact or interconnect\$3).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
16	L1 8	5770	17 and (CMP or polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

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17	L1 9	525	18 and ((isolation near trench\$2) or STI)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
18	L2 0	0	19 and (part\$3 near remov\$3) near (isolat\$3 or insulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
19	L2 1	21246	isolation near trench\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
20	L2 2	1116	21 and contact near opening	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
21	L2 3	700	22 and (CMP or polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
22	L2 4	9	23 and (part\$3 near remov\$3) near (isolat\$3 or insulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
23	L2 5	9	23 and (partial\$2 near (etch\$3 or remov\$3)) near (isolat\$3 or insulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB